

FORM PTO-1449	U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE	ATTY. DOCKET NO. MICRON.182A	APPLICATION NO. 09/973,854
INFORMATION DISCLOSURE STATEMENT BY APPLICANT  (USE SEVERAL SHEETS IF NECESSARY)		APPLICANT Chopra et	COPY OF PAPERS ORIGINALLY FILED
		FILING DATE October 9, 2001	

## U.S. PATENT DOCUMENTS

EXAMINER INITIAL	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE (IF APPROPRIATE)

## FOREIGN PATENT DOCUMENTS

EXAMINER INITIAL	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION	
						YES	NO

EXAMINER INITIAL	OTHER DOCUMENTS (INCLUDING AUTHOR, TITLE, DATE, PERTINENT PAGES, ETC.)
dm	A Dinesh Chopra and Ian Ivar Suni, "An Optical Method for Monitoring Metal Contamination during Aqueous Processing of Silicon Wafers", <i>J. Electrochem. Soc.</i> , Vol. 145, No. 5, May 1998, pp. 1688-1692.
dm	B Dinesh Chopra, Ian Ivar Suni and Ahmed A. Busnaina, "Cu Dissolution from Si(111) into an SC-1 Process Solution", <i>J. Electrochem. Soc.</i> , Vol. 145, No. 4, April 1998, pp. L60-61.
dm	C Peter Singer, Editor-in-Chief, "Copper CMP: A Question of Tradeoffs", <i>Semiconductor International</i> , <a href="http://www.semiconductor.net/semiconductor/issues/issues/2000/200005/six0005cmp.asp">http://www.semiconductor.net/semiconductor/issues/issues/2000/200005/six0005cmp.asp</a> , May 2000, 11 pages.
dm	D "The CMP Business Unit", Rodel Products, <a href="http://www.rodel.com/Products/CMP.asp">http://www.rodel.com/Products/CMP.asp</a> , 1998-2000, 13 pages.
dm	E Kurt Hery and Dr. David P. Norwood, "Study of the Refractive Index Increment of Polyelectrolytes and Neutral Polymers", Southeastern Louisiana University, <a href="http://www.selu.edu/Academics/Arts&amp;Sciences/connections/journal1/k-hery/Hery.html">http://www.selu.edu/Academics/Arts&amp;Sciences/connections/journal1/k-hery/Hery.html</a> , 7 pages.
dm	F Iqbal Ali and Sudipto R. Roy, "Pad conditioning in interlayer dielectric CMP", Texas Instruments, <a href="http://www.semipark.co.../Pad%20conditioning%20in%20interlayer%20dielectric%20CMP.ht">http://www.semipark.co.../Pad%20conditioning%20in%20interlayer%20dielectric%20CMP.ht</a> , June 1, 1997, 6 pages.
dm	G "Chemical Mechanical Planarization (CMP)", S.C. Solutions, <a href="http://www.scsolutions.com/smp.html">http://www.scsolutions.com/smp.html</a> , 4 pages.

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